

# AT468

## Rotary Scan-Pack Handler for Lead & Leadless Packages

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The AT468 is a high speed multi-function scan-pack handler engineered for Lead and Leadless packages. This fully automated design consists of a primary 24-station rotary turret coupled with a secondary multi-station inspection table.

The modular concept allows for media transfer flexibility, supporting a wide range of I/O configurations. These include plastic tube, multi-channel metal magazine, vibratory bowl, Jedec tray and reel. Single or multiple test stations can also be integrated into the AT468.

STI's proprietary vision technologies are employed to provide ONE Vision Solution for all package types. This architecture provides our customers with a powerful one-stop strategy, facilitating standardisation of quality assurance inspection techniques.

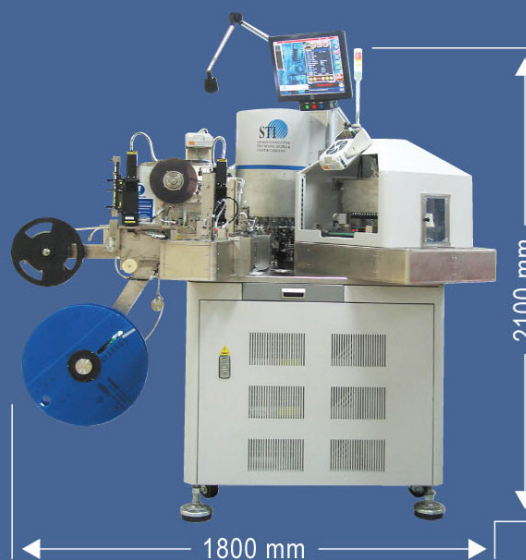
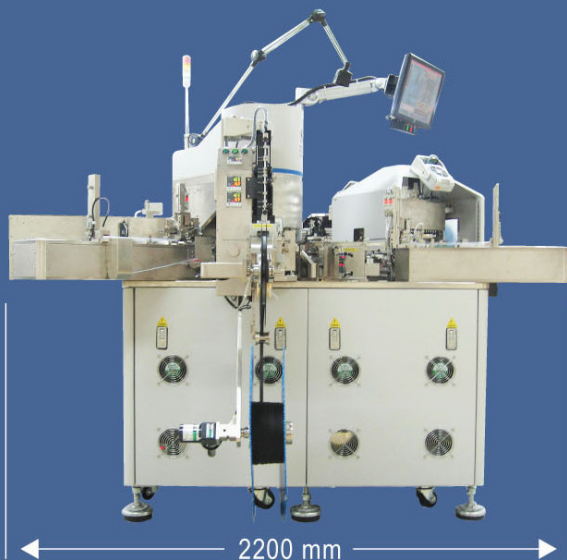
# AT468 Specifications

SPECIFICATIONS	DESCRIPTION
Package Type	Leadless: eg QFN, NLF, LGA Lead: eg SOIC, TSSOP
Package Size	3x3 to 12x12 mm (Leadless) Up to 12x18mm (Lead)
<b>NOTE: <sup>1</sup>AT468 can be configured to handle 1-6mm leadless device, SOT &amp; MSOP</b>	
UPH	Up to 35,000 (depending on package type)
Optional I/O	Metal Magazine Loader Metal Magazine Unloader Bowl Feeder Plastic Tube Loader <sup>2</sup> Plastic Tube Unloader <sup>2</sup> Jedec Tray Loader* Jedec Tray Unloader# Tape & Reel Output <sup>3</sup> Tube Reject Sorter (Up to 8 tubes) Bin Reject Sorter (1/4/8 bins) In-Pocket Reject Sorter
User Interface	Windows platform with GUI Full machine diagnostics
<b>FACILITIES</b>	
Footprint	2.2L x 1.8W x 2.1H (m)
Weight	1400 kg
AC Power Supply	230V
Air Supply	6 bar minimum
Vacuum	-850 mbar minimum
<sup>1</sup> Tape Width:	8 - 16mm
<sup>2</sup> Tube Width:	5 - 14mm
Tube Width:	400 - 550mm
Tube Stack:	30 tubes
<sup>3</sup> Tape Width:	8 - 24 mm
* Minimum Row Pitch:	7.5 mm
# Minimum Column Pitch:	6.5mm

TEST INTERFACE	
No. Of Test Sites	1, 2, 4 or 8
Interface	Serial, I/O, GPIB
Optional	Laser Mark

INSPECTION	DETAILS
Top View	Mark / Orientation
5-Side (Sides & Bottom)	Package Dimensions Pad Length & Width Pad Pitch Pad Coplanarity Pad Height
3D Lead	Bent Coplanarity Pitch Stand-off Tip to Tip
In-Pocket	Device present Mark Orientation Empty Pocket Out of Pocket
Post Seal	Sealing Quality Part Present Orientation
PVI	Chip Void Crack Mold Flash Scratch

## Layout



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